

Amendments to the Claims:

The following Listing of Claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1-26. (Canceled)

27. (new) An acrylic thermally conductive composition comprising:
a thermally conductive filler; and
a crystalline aliphatic acrylic polymer comprising at least 50 wt% of a homopolymer or copolymer of one or more crystalline aliphatic acrylic monomers containing 18 or more carbon atoms.

28. (new) A composition according to claim 27 wherein the crystalline acrylic monomers are selected from octadecyl (meth)acrylate, nonadecyl(meth)acrylate, icosanyl(meth)acrylate, heicosanyl(meth)acrylate, docosanyl(meth)acrylate, tricosanyl(meth)acrylate, tetracosanyl(methacrylate), octododecyl(meth)acrylate, and combinations thereof.

28. (new) A composition according to claim 27 wherein the crystalline acrylic polymer further comprises a homopolymer or copolymer of one or more noncrystalline aliphatic acrylic monomers.

29. (new) A composition according to claim 28 wherein the noncrystalline acrylic monomers contain 12 carbons or less.

30. (new) A composition according to claim 29 wherein the noncrystalline acrylic monomers are selected from ethyl (meth)acrylate, butyl (meth)acrylate, hexyl(meth)acrylate, 2-ethylhexyl (meth)acrylate, octyl (meth)acrylate, isoctyl (meth)acrylate, decyl (meth)acrylate, dodecyl (meth)acrylate, and combinations thereof.

31. (new) A composition according to claim 27 wherein the crystalline acrylic polymer has a melting point of 25°C or higher and 100°C or lower.
32. (new) A thermally conductive sheet obtained from a composition according to claim 27.
33. (new) A laminate comprising:
an electronic part;
a thermally conductive sheet according to claim 27 having a first side and a second side,
wherein the first side is in contact with the electronic part; and
a heat sink or heat radiator in contact with the second side of the thermally conductive sheet.
34. (new) A laminate according to claim 33 wherein the electronic part is selected from a power transistor, a graphic IC, chip sets, memory chips, central processing units, and combinations thereof.
35. (new) A laminate according to claim 33 wherein the thickness of the thermally conductive sheet is less than 10 mm.
36. (new) A laminate according to claim 35 wherein the thickness of the thermally conductive sheet is less than 5 mm.